1.	Record Nr.	UNINA9910484726403321
	Titolo	3D microelectronic packaging : from architectures to applications / / editors, Yan Li, Deepak Goyal
	Pubbl/distr/stampa	Singapore : , : Springer, , [2021] ©2021
	ISBN	981-15-7090-6
	Edizione	[2nd edition 2021.]
	Descrizione fisica	1 online resource (XVII, 622 p. 299 illus., 205 illus. in color.)
	Collana	Springer Series in Advanced Microelectronics, , 1437-0387 ; ; 64
	Disciplina	929.374
	Soggetti	Biotechnology Electronics Electronics - Materials Microelectronics Microelectronics - Packaging Nanotechnology Electronic circuits Optical materials
	Lingua di pubblicazione	Inglese
	Formato	Materiale a stampa
	Livello bibliografico	Monografia
	Note generali	Includes index.
	Nota di contenuto	1. Introduction to 3D microelectronic packaging -- 2. 3D packaging architecture and assembly process design -- 3. Fundamentals of TSV processing and reliability -- 4. Mechanical properties of TSV -- 5. Atomistic View of TSV Protrusion/Intrusion -- 6. Fundamentals and failures in Die preparation for 3D packaging -- 7. Direct Cu to Cu bonding and other alternative interconnects in 3D packaging -- 8. Emerging hybrid bonding techniques for 3D packaging -- 9. Fundamental of Thermal Compressive Bonding process, advanced epoxy, and flux materials in 3D packaging -- 10. Fundamentals of solder alloys in 3D packaging -- 11. Fundamentals of electro migration in interconnects of 3D packages -- 12. Fundamentals of heat dissipation in 3D packaging -- 13. Fundamentals of advanced materials and process in substrate technology -- 14. New substrate technologies for 3D packaging. -15. Thermal mechanical and moisture modeling in 3D packaging -- 16. Stress and Strain measurements in 3D packaging

		-- 17.Processing and Reliability of Solder Interconnections in Stacked Packaging -- 18. Interconnect Quality and Reliability of 3D Packaging -- 19. Fundamentals of automotive reliability of 3D packages -- 20. Fault isolation and failure analysis of 3D packaging.
	Sommario/riassunto	This book offers a comprehensive reference guide for graduate students and professionals in both academia and industry, covering the fundamentals, architecture, processing details, and applications of 3D microelectronic packaging. It provides readers an in-depth understanding of the latest research and development findings regarding this key industry trend, including TSV, die processing, micro-bumps for LMI and MMI, direct bonding and advanced materials, as well as quality, reliability, fault isolation, and failure analysis for 3D microelectronic packages. Images, tables, and didactic schematics are used to illustrate and elaborate on the concepts discussed. Readers will gain a general grasp of 3D packaging, quality and reliability concerns, and common causes of failure, and will be introduced to developing areas and remaining gaps in 3D packaging that can help inspire future research and development. .
2.	Record Nr.	UNISA996323650103316
	Titolo	Revista brasileira da educação profissional e tecnológica
	Pubbl/distr/stampa	Brasília, : Ministério da Educação, Secretaria de Educação Profissional e Tecnológica, 2008- Natal, Rio Grande do Norte, Brasil : , : Editora do Instituto Federal de Educação, Ciência e Tecnologia do Rio Grande do Norte
	Descrizione fisica	1 online resource
	Soggetti	Vocational education - Brazil Professional education - Brazil Technical education - Brazil Vocational education Technical education Professional education Periodicals. Brazil
	Lingua di pubblicazione	Portoghese

Formato	Materiale a stampa
Livello bibliografico	Periodico
Note generali	Refereed/Peer-reviewed

3.	Record Nr.	UNINA9910299606503321
	Titolo	Electric Vehicle Business Models : Global Perspectives / / edited by David Beeton, Gereon Meyer
	Pubbl/distr/stampa	Cham : , : Springer International Publishing : , : Imprint : Springer, , 2015
	ISBN	3-319-12244-4
	Edizione	[1st ed. 2015.]
	Descrizione fisica	1 online resource (266 p.)
	Collana	Lecture Notes in Mobility, , 2196-5544
	Disciplina	333.79 338926 388 621.042
	Soggetti	Transportation Management Industrial management Automotive engineering Energy policy Innovation/Technology Management Automotive Engineering Energy Policy, Economics and Management
	Lingua di pubblicazione	Inglese
	Formato	Materiale a stampa
	Livello bibliografico	Monografia
	Note generali	Description based upon print version of record.
	Nota di bibliografia	Includes bibliographical references at the end of each chapters.
	Nota di contenuto	EV business models in a wider context: balancing change and continuity in the automotive industry -- Four business models for a fast commercialization of plug-in cars -- Electrification of the Powertrain in Automotive Applications: "Technology Push" or "Market Pull"? -- Identification of market models and associated billing strategies for the provision of EV charging services -- Business Case

for EV charging on the Motorway Network in Denmark -- Pricing Plug-in Electric Vehicle Recharging in Multi-Unit Dwellings: Financial Viability and Fueling Costs -- Solutions and Business Models for Wireless Charging of Electric Vehicles -- Electric Vehicles as Grid Support -- Energy Efficiency in Electric and Plug-in Hybrid Electric Vehicles and its Impact on Total Cost of Ownership.

Sommario/riassunto

This contributed volume collects insights from industry professionals, policy makers and researchers on new and profitable business models in the field of electric vehicles (EV) for the mass market. This book includes approaches that address the optimization of total cost of ownership. Moreover, it presents alternative models of ownership, financing and leasing. The editors present state-of-the-art insights from international experts, including real-world case studies. The volume has been edited in the framework of the International Energy Agency’s Implementing Agreement for Cooperation on Hybrid and Electric Vehicles (IA-HEV). The target audience primarily comprises practitioners and decision makers but the book may also be beneficial for research experts and graduate students. .